



## SGM4871

### 2.4W Audio Power Amplifier with Shutdown Mode

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#### GENERAL DESCRIPTION

The SGM4871 is a mono bridged audio power amplifier that is designed for portable communication device applications and demanding applications in mobile phones. SGM4871YPS8 is capable of delivering 2.4W of continuous average power to an 4Ω load with less than 10% distortion (THD) from a 5V battery voltage. It operates from 2.5V to 5.5V power supply.

The SGM4871's micro-power shutdown mode ( $I_{SD} = 0.07\mu A$  TYP) is activated when  $V_+$  is applied to the SHDN pin. Since the SGM4871 does not require output coupling capacitors, bootstrap capacitors, or snubber networks, it is ideally suited for low-power portable systems that require minimum volume and weight.

The SGM4871 is unity-gain stable and can be configured by external gain-setting resistors. Additionally, the SGM4871 features an internal thermal shutdown protection mechanism.

The SGM4871 is available in SO-8 and SO-8(PP) packages. It operates over an ambient temperature range of -40°C to +85°C.

#### FEATURES

- PO at 10% THD+N, 1kHz  
SGM4871YPS8: 2.4W (TYP) to 4Ω Load  
All other SGM4871 Packages: 1.5W (TYP) to 8Ω Load
- Unity Gain Stable
- 2.5V to 5.5V Operation
- Shutdown Current: 0.07μA (TYP)
- Thermal Overload Protection Circuitry
- No Output Coupling Capacitors, Bootstrap Capacitors or Snubber Networks Required
- External Gain Configuration Capability
- -40°C to +85°C Operating Temperature Range
- Small SO-8 and SO-8(PP) Packages

#### APPLICATIONS

Portable System  
Wireless Handset  
Mobile Phone  
PDAs



PACKAGE/ORDERING INFORMATION

MODEL	ORDER NUMBER	PACKAGE DESCRIPTION	PACKAGE OPTION	MARKING INFORMATION
SGM4871	SGM4871YPS8/TR	SO-8(PP)	Tape and Reel, 2500	SGM4871YPS8
	SGM4871YS8/TR	SO-8	Tape and Reel, 2500	SGM4871YS8

ABSOLUTE MAXIMUM RATINGS

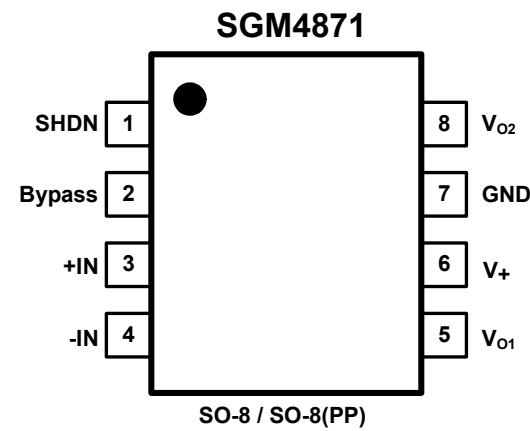
Supply Voltage .....5.5V  
Input Voltage..... - 0.1V to (V<sub>+</sub>) + 0.1V  
Storage Temperature Range..... - 65°C to +150°C  
Junction Temperature ..... 150°C  
Operating Temperature Range.....- 40°C to +85°C  
Lead Temperature Range (Soldering 10 sec)  
.....260°C  
ESD Susceptibility  
HBM.....2000V  
MM.....200V

NOTE  
1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.  
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PIN CONFIGURATION (Top View)



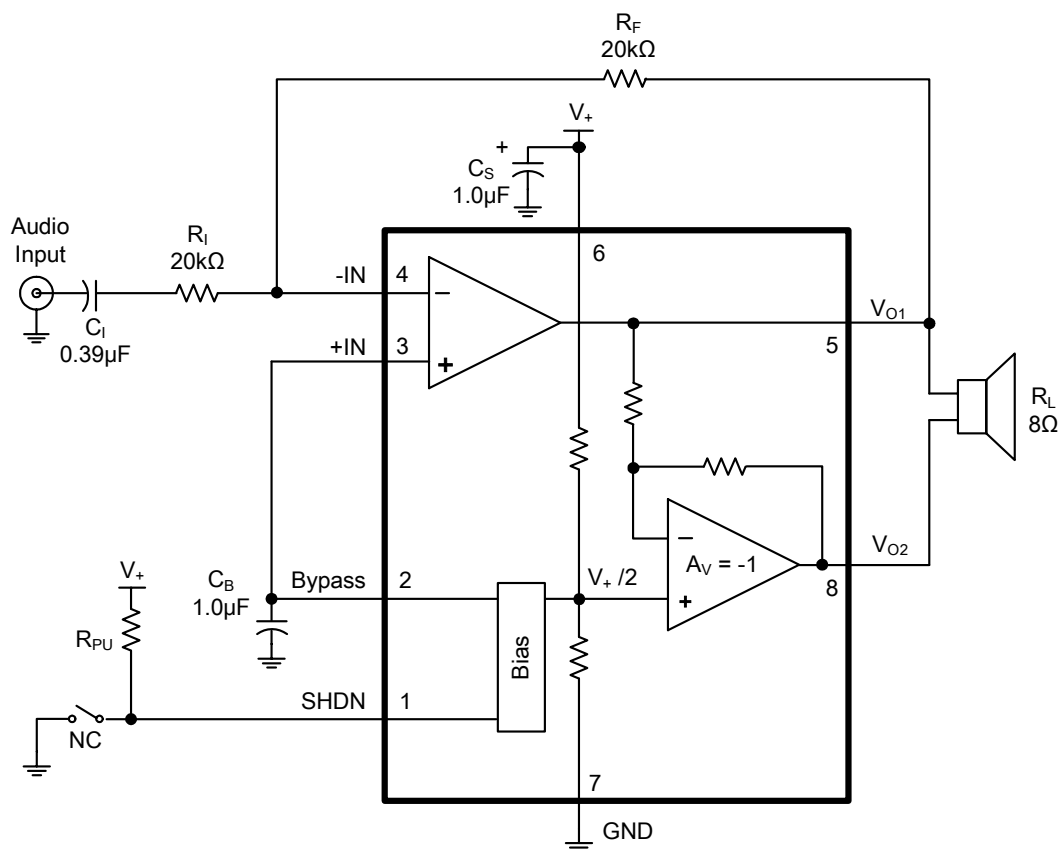
**ELECTRICAL CHARACTERISTICS**

The following specifications apply for  $T_A = 25^\circ\text{C}$ ,  $V_+ = 5\text{V}$  and  $R_L = 8\Omega$ , unless otherwise specified.

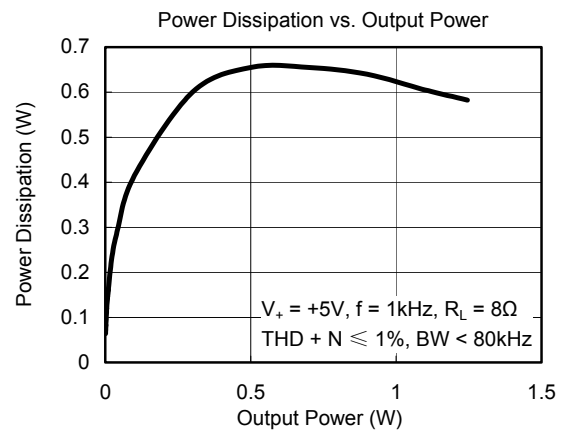
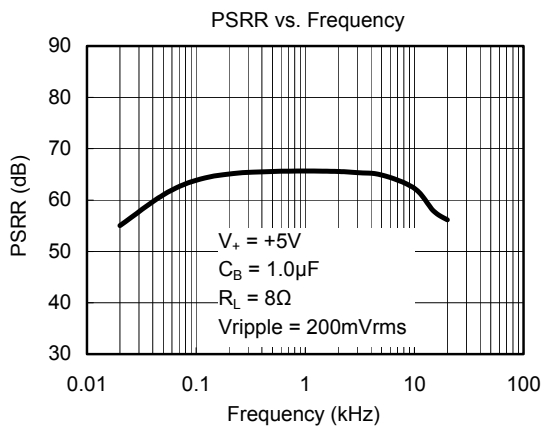
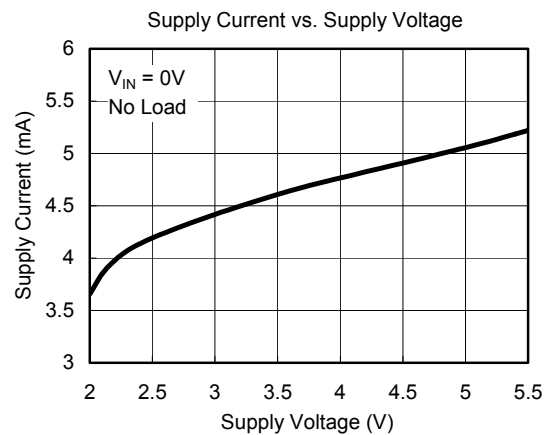
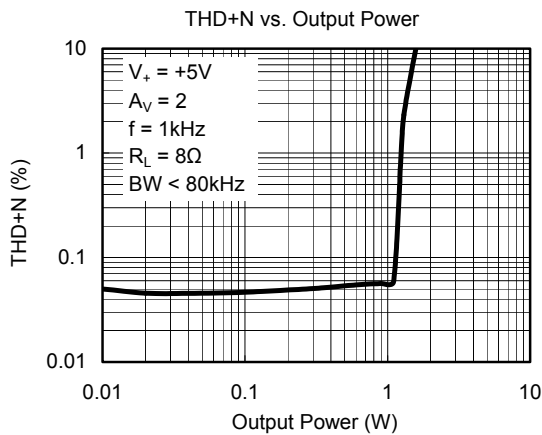
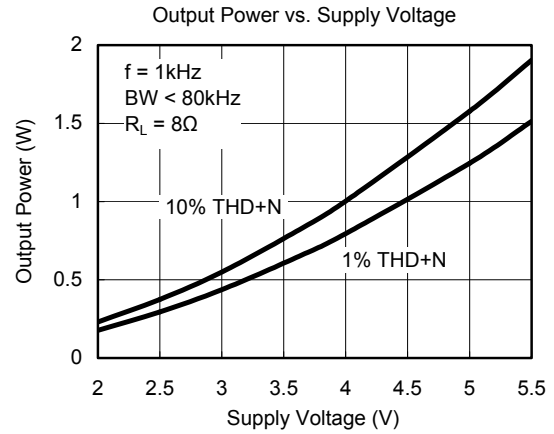
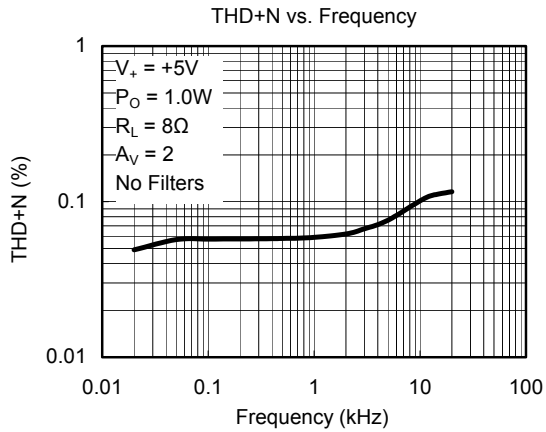
PARAMETER	SYMBOL	CONDITIONS		SGM4871			UNITS
				MIN	TYP	MAX	
Supply Voltage	$V_+$			2.5		5.5	V
Output Offset Voltage	$V_{OS}$				5.5	65	mV
Quiescent Power Supply Current	$I_Q$	$V_{SHDN} = \text{GND}$	No Load		5.2	9	mA
			$R_L = 8\Omega$		5.3		
Shutdown Current	$I_{SD}$	$V_+ = 5.0\text{V}$ , $V_{SHDN} = 5.0\text{V}$ , $I_O = 0\text{mA}$			0.07	2	$\mu\text{A}$
Shutdown Voltage Input High	$V_{SDIH}$			1.2			V
Shutdown Voltage Input Low	$V_{SDIL}$					0.4	
Output Power (4 $\Omega$ )	$P_O$	$f = 1\text{kHz}$ , $\text{THD+N} = 1\%$			1.9		W
		$f = 1\text{kHz}$ , $\text{THD+N} = 10\%$			2.4		W
Output Power (8 $\Omega$ )	$P_O$	$f = 1\text{kHz}$ , $\text{THD+N} = 1\%$			1.2		W
		$f = 1\text{kHz}$ , $\text{THD+N} = 10\%$			1.5		W
Total Harmonic Distortion + Noise	THD+N	$20\text{Hz} < f < 20\text{kHz}$ , $R_L = 8\Omega$ , $P_O = 1\text{W}$			0.2		%
Power Supply Rejection Ratio	PSRR	$V_{SHDN} = \text{GND}$ , $V_+ = 4.9\text{V}$ to $5.1\text{V}$			70		dB

Specifications subject to changes without notice.

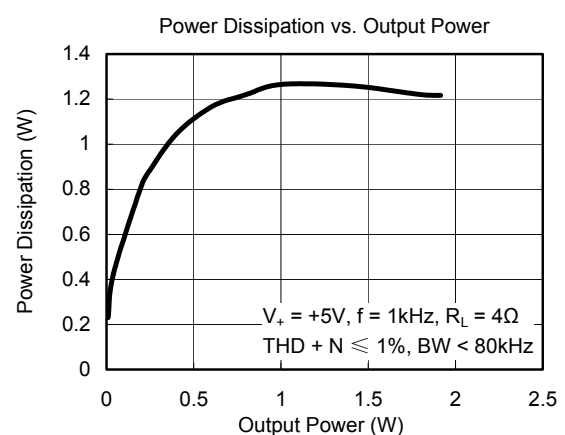
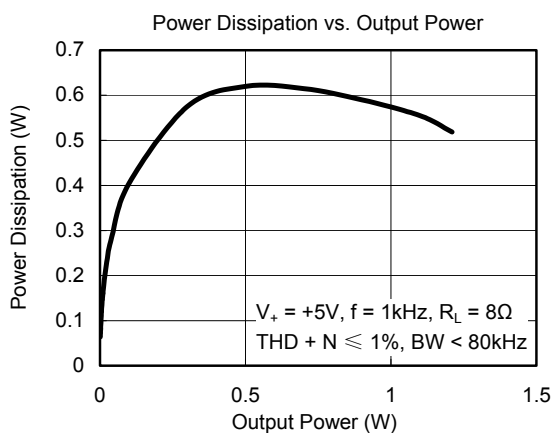
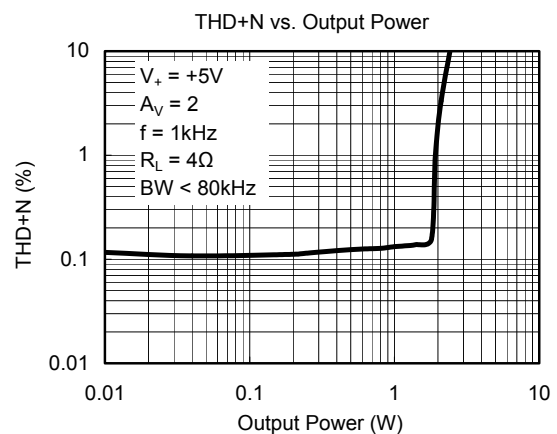
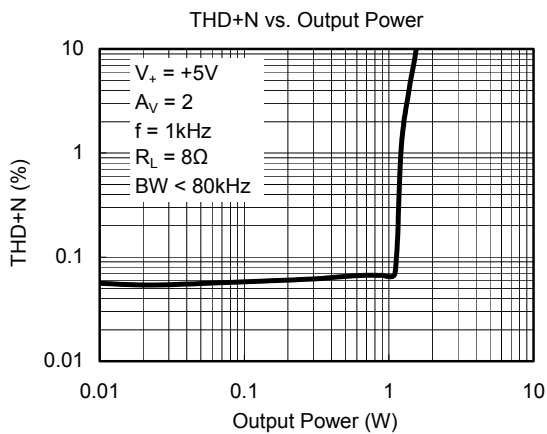
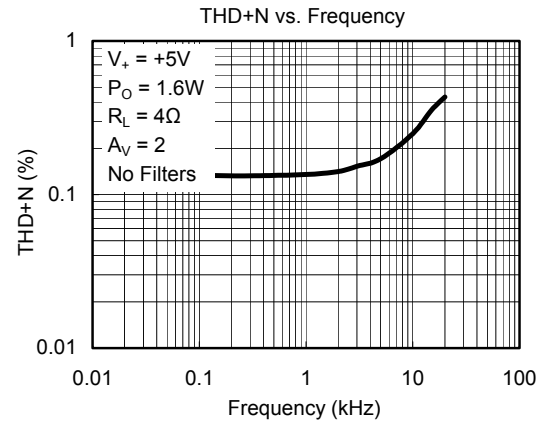
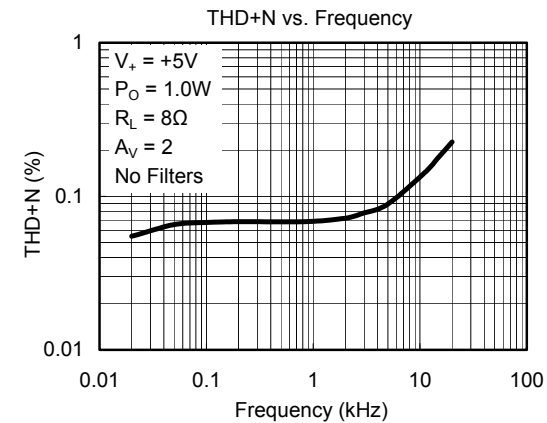
## TYPICAL APPLICATION



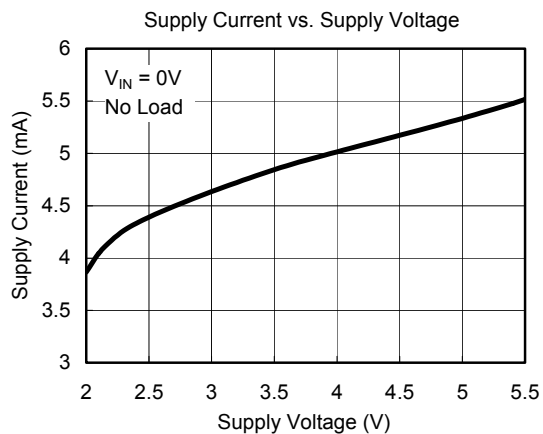
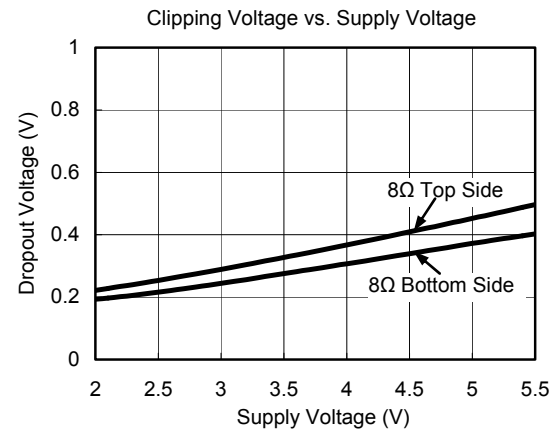
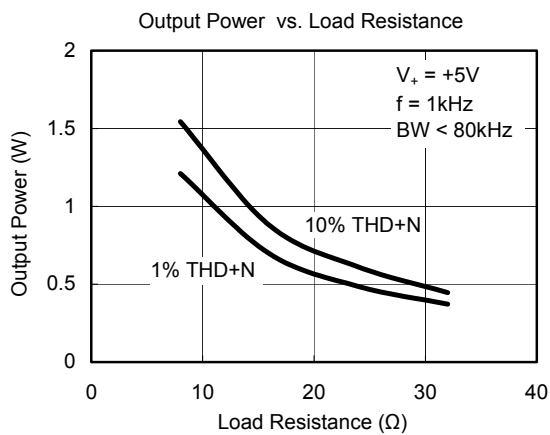
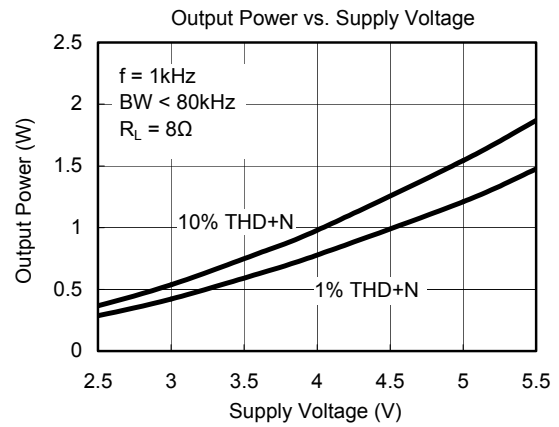
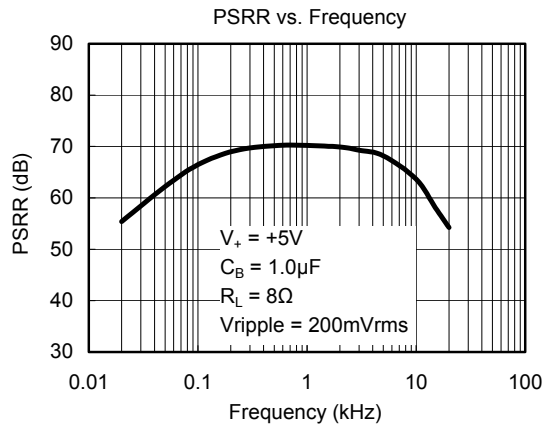
## TYPICAL PERFORMANCE CHARACTERISTICS (SGM4871YS8)



## TYPICAL PERFORMANCE CHARACTERISTICS (SGM4871YPS8)



## TYPICAL PERFORMANCE CHARACTERISTICS (SGM4871YPS8) Cont.



## APPLICATION NOTES

### PCB Design Recommendations (Thermal Design Considerations)

SGM4871YPS8 is capable of delivering 2.4W of continuous average power to an 4Ω load when provide a thermal design considerations

#### Thermal Land

The SO-8(PP) thermal land is a metal (normally copper) region centrally located under the package and on top of the PCB. It has a rectangular or square shape and should match the dimensions of the exposed pad on the bottom of the package (1:1 ratio).

For certain high power applications, the PCB land may be modified to a "dog bone" shape that enhances thermal performance. The packages used with the "dog bone" lands will be a dual inline configuration. (See Figure 1).

Top View

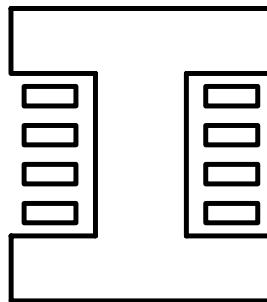


Figure1. Dog Bone

#### Thermal Vias

Thermal vias are necessary. They conduct heat from the exposed pad of the package to the ground plane. The number of vias is application specific and is dependent upon electrical requirements and power dissipation.

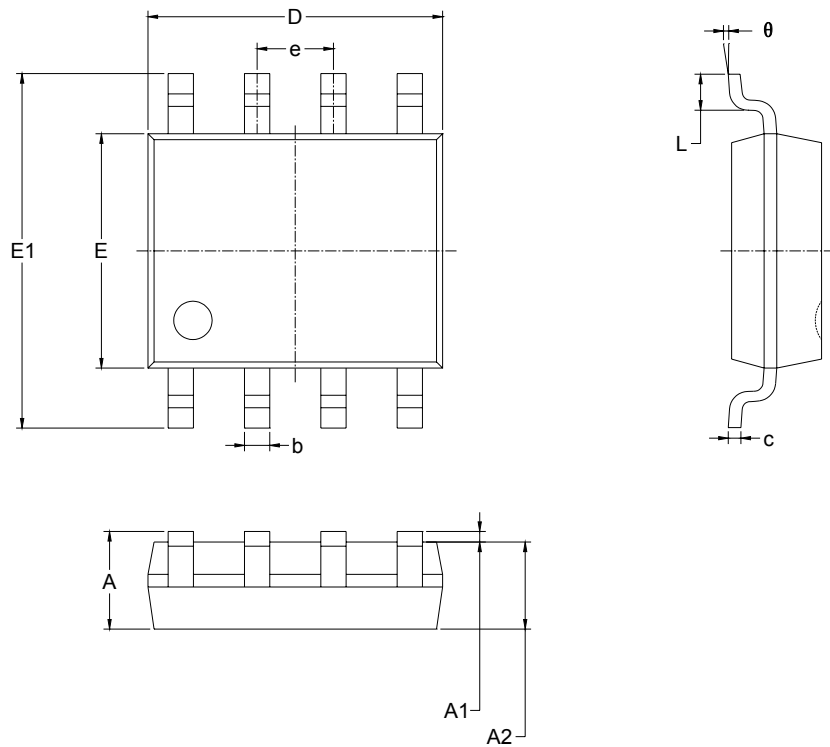
The via diameter should be 0.2 mm to 0.33 mm with 1oz. copper via barrel plating. It is important to plug the via to avoid any solder wicking inside the via during the soldering process. The thermal vias can be tented with solder mask on the top surface of the PCB. The solder mask diameter should be at least 75 microns (or 3 mils) larger than the via diameter. The solder mask thickness should be the same across the entire PCB.

A package thermal performance may be improved by increasing the number of vias.



## PACKAGE OUTLINE DIMENSIONS

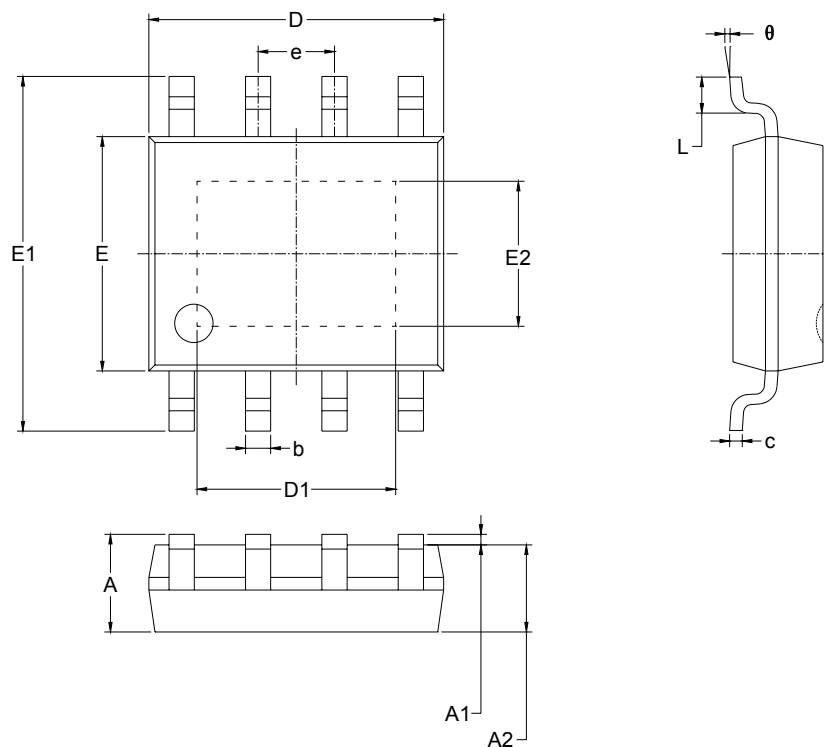
## SO-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## PACKAGE OUTLINE DIMENSIONS

## SO-8(PP)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.050	0.150	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
D1	3.202	3.402	0.126	0.134
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
E2	2.313	2.513	0.091	0.099
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

10/2009 REV. A

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